In the Claims:

Please cancel claims 21-22 and 35. Please add new claims 42-43. The claims are as follows.

1-9 (Canceled)

10. (Previously presented) A method of forming an electronic package, comprising the steps of:

providing an electronic component having a first featurized surface and a second surface; and

removing a portion of the second surface such that the second surface is substantially arcuate, wherein a distance between the first surface and the second surface continuously increases from a periphery of the electronic component to near a center of the electronic component.

11. (Original) The method of claim 10, further comprising the steps of:

electrically mounting the first featurized surface of the electronic component to a substrate; and

mounting an element to the second surface of the electronic component.

12. (Original) The method of claim 10, further comprising the step of:

removing at least one edge from a portion of the electronic component.

13. (Original) The method of claim 11, wherein the substrate is a carrier.

14. (Original) The method of claim 11, wherein the element is a cover plate.

15. (Original) The method of claim 11, wherein the element is a heat sink.

16. (Original) The method of claim 11, wherein the element is mounted to the second surface of the electronic component using an adhesive.

17. (Original) The method of claim 16, wherein the adhesive is a thermally conductive reflowable material.

18. (Original) The method of claim 10, wherein the step of removing a portion of the second surface is performed using a profiling tool.

19. (Original) The method of claim 18, wherein the profiling tool has a concave profiling surface.

20-35. (Canceled)

36. (Previously presented) A method of forming an electronic package, comprising the steps of:

providing a substrate having an opening therein; and

forming an electronic component mounted within the opening of the substrate, the electronic component having a non-planar first surface and a second arcuate surface opposing the first surface and having a contour such that a distance between the first surface and the second arcuate surface continuously increases from a periphery of the electronic component to near a center of the electronic component.

37. (Previously presented) The method of claim 36, further comprising mounting an element to the second surface of the electronic component.

38. (Previously presented) The method of claim 37, wherein the element is a cover plate.

39. (Previously presented) The method of claim 37, wherein the element is a heat sink.

40. (Previously presented) The method of claim 37, wherein the element is mounted to the second surface of the electronic component using an adhesive.

41. (Previously presented) The method of claim 40, wherein the adhesive is a thermally conductive reflowable material.

42. (New) A method of forming semiconductor chips, comprising the steps of:

providing a semiconductor wafer having a first featurized surface and a second surface;

scoring the wafer to generate a two-dimensional array of sections of the wafer defined by score lines on the wafer;

removing a portion of the second surface in each section such that the second surface is substantially arcuate in each section, wherein said removing the portion of the second surface in each section results in each section having a distance between the first surface and the second surface continuously increasing from a periphery of each section to near a center of each section; and

following said removing the portion of the second surface in all sections of the wafer, dicing the wafer along the score lines to separate the sections from one another such that a semiconductor chip is formed from each separated section.

43. (New) The method of claim 42, wherein said removing comprises the steps of:

passing a profiling tool across the wafer in a first direction to perform a first stage of said removing the portion of the second surface in each section; and

passing the profiling tool across the wafer in a second direction to perform a second stage of said removing the portion of the second surface in each section to complete said removing, wherein the first and second directions are mutually orthogonal.